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| flexible and (semiconductive or semiconductor) and organic and polymer |

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1 **A flexible conjugated polymer laser using 2D distributed feedback**
Riechel, S.; Kallinger, C.; Lemmer, U.; Feldmann, J.; Gombert, A.; Wittwer, V.; Scherf, U.;
Lasers and Electro-Optics, 1999. CLEO '99. Summaries of Papers Presented at the Conference on , 23-28 May 1999
Page(s): 465 -466

[Abstract]   [PDF Full-Text (224 KB)] **IEEE CNF**

2 **Roll-up displays: fact or fiction?**
Collins, L.;
IEE Review , Volume: 49 Issue: 2 , Feb. 2003
Page(s): 42 -45

[Abstract]   [PDF Full-Text (340 KB)] **IEE JNL**

3 **An organic thin film transistor backplane for flexible liquid crystal displays**
Sheraw, C.D.; Nichols, J.A.; Gundlach, D.J.; Huang, J.R.; Kuo, C.C.; Klauk, H.; Jackson, T.N.; Kane, M.G.; Campi, J.; Cuomo, F.P.; Greening, B.K.;
Device Research Conference, 2000. Conference Digest. 58th DRC , 19-21 June 2000
Page(s): 107 -108

[Abstract]   [PDF Full-Text (180 KB)] **IEEE CNF**

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| security AND (strip OR thread) AND (IC OR chip OR (integrated AND circuit)) |

| Search Again |

Results:
Journal or Magazine = **JNL**   Conference = **CNF**   Standard = **STD**

1 **Crafting a Java virtual machine in silicon**
Hardin, D.S.
IEEE Instrumentation & Measurement Magazine , Volume: 4 Issue: 1 ,
March 2001
Page(s): 54 -56

[Abstract]   [PDF Full-Text (460 KB)] **JNL**

2 **Smart-cards-a cost-effective solution against electronic fraud**

Lassus, M.
Security and Detection, 1997. ECOS 97., European Conference on ,
1997
Page(s): 81 -85

[Abstract]   [PDF Full-Text (340 KB)] **CNF**

3 **Paper based document security-a review**
van Renesse, R.L.
Security and Detection, 1997. ECOS 97., European Conference on ,
1997
Page(s): 75 -80

[Abstract]   [PDF Full-Text (508 KB)] **CNF**

4 **Crypt graphic smart cards**
Naccache, D.; M'Raihi, D.
IEEE Micro , Volume: 16 Issue: 3 , June 1996
Page(s): 14, 16 -24

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(semiconductive AND organic AND polymer)

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76 **Migration of vinyl acetate from semiconductive to insulation
of power cables**
Haridoss, S.
Electrical Insulation, 1990., Conference Record of the 1990 IEEE
International Symposium on , 1990
Page(s): 281 -285

[Abstract]   [PDF Full-Text (328 KB)] **CNF**

77 **A new concept for medium-voltage cables: improved
voltage life of belt-type cables**
Kreuger, F.H.; Morshuis, P.H.F.; van de Laar, A.M.F.
Electrical Insulation, IEEE Transactions on [see also Dielectrics and
Electrical Insulation, IEEE Transactions on] , Volume: 24 Issue: 6 ,
Dec. 1989
Page(s): 1063 -1070

[Abstract]   [PDF Full-Text (468 KB)] **JNL**

78 **Dielectric breakdown strength affected by the lamellar
configuration in XLPE insulation at a semiconducting interface**
Okamoto, T.; Ishida, M.; Hozumi, N.
Electrical Insulation, IEEE Transactions on [see also Dielectrics and
Electrical Insulation, IEEE Transactions on] , Volume: 24 Issue: 4 ,
Aug. 1989
Page(s): 599 -607

[Abstract]   [PDF Full-Text (644 KB)] **JNL**

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1 **Plastic electronics based on semiconducting polymers**
*Schrodner, M.; Sensfuss, S.; Roth, H.-K.; Stohn, R.-I.; Clemens, W.;
Bernds, A.; Fix, W.*
Polymers and Adhesives in Microelectronics and Photonics, 2001. First
International IEEE Conference on , 2001
Page(s): 91 -94

[Abstract]   [PDF Full-Text (393 KB)] **CNF**

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2 **Will polymer electronics change the electronics industry?**
Hofstraat, H.
Polymers and Adhesives in Microelectronics and Photonics, 2001. First
International IEEE Conference on , 2001
Page(s): 1 -8

[Abstract]   [PDF Full-Text (713 KB)] **CNF**

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3 **Manufacturability and reliability of non-halogenated molding
compounds**
*Cada, L.G.; Lalanto, R.; Coronel, G.; San Gregorio, N.; Asis, D.; Ong,
G.; Ducusin, C.; Desengano, R.; Llamas, T.; Decena, R.; Canares, N.;
Reyes, A.; Miciano, P.*
Electronics Packaging Technology Conference, 2000. (EPTC 2000).
Proceedings of 3rd , 2000
Page(s): 15 -20

[Abstract]   [PDF Full-Text (324 KB)] **CNF**

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4 **P lymer pt electr nics and semiconductor grafting for
aer space applications**

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1 **Plastic electronics based on semiconducting polymers**
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Bernds, A.; Fix, W.
Polymers and Adhesives in Microelectronics and Photonics, 2001. First
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[Abstract]   [PDF Full-Text (393 KB)] **CNF**

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2 **Will polymer electronics change the electronics industry?**
Hofstraat, H.
Polymers and Adhesives in Microelectronics and Photonics, 2001. First
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BRS	L2	0	(Krul-Johannes.in. Hart-Cornelius-Maria.in. DeLeeuw-Dagobert-Michel.in. DeHesse-Wilhelm-Bernardus.in. Matters-Marco.in.) and @pd>20030715	USPAT; US-PGPUB; EPO; JPO	2003/07/27 18:01			0
BRS	L3	0	(Krul-J.in. Hart-C.in. DeLeeuw-D.in. DeHesse-W.in. Matters-M.in.) and @pd>20030715	DERWENT	2003/07/27 18:01			0
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BRS	L5	0	((paper cardboard) near5 (IC chip)) same (integrated adj circuit) and @pd>20030715	USPAT; US-PGPUB	2003/07/27 18:02			0
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BRS	L10	0	(conduct$3 near5 (security near2 (strip thread))) and (hologram optical$2 foil kinegram) and @pd>20030715	USPAT; US-PGPUB	2003/07/27 18:04			0
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BRS	L12	0	(security near2 (strip thread)) same (hologram holographic) and @pd>20030715	USPAT; US-PGPUB	2003/07/27 18:05			0
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BRS	L15	0	(organic near2 polymer) same polyimide same polyaniline and @pd>20030715	USPAT; US-PGPUB	2003/07/27 18:07			0
BRS	L16	0	(ic circuit semiconductive semiconductor) same (polyimide adj10 polyaniline) and @pd>20030715	USPAT; US-PGPUB	2003/07/27 18:07			0
BRS	L17	1	polyimide adj10 polyaniline and @pd>20030715	USPAT; US-PGPUB	2003/07/27 18:07			0
BRS	L18	0	(security near2 (strip thread)) same (size thickness width thick) and @pd>20030715	USPAT; US-PGPUB	2003/07/27 18:08			0
BRS	L19	5	(banknote$1 (bank adj note$1) passport (security adj1 (document$1 paper$1)) same (IC chip circuit semiconductor semiconducting) and @pd>20030715	USPAT; US-PGPUB	2003/07/27 18:08			0

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BRS	L20	0	((banknote$1 (bank adj note$1) passport (security adj1 (document$1 paper$1 thread$1 strip$1)) same (IC chip circuit semiconductor semiconducting)) not ((banknote$1 (bank adj note$1) passport (security adj1 (document$1 paper$1)) same (IC chip circuit semiconductor semiconducting)) and @pd>20030715	USPAT; US-PGPUB	2003/07/27 18:10			0
BRS	L21	0	(banknote$1 (bank adj note$1) passport (security adj1 (document$1 paper$1 thread$1 strip$1)) same (IC chip circuit semiconductor semiconducting) and @pd>20030715	EPO; JPO; DERWENT; IBM_TDB	2003/07/27 18:10			0
BRS	L22	1	(flexible flexibility bend$4) near5 (ic (integrated adj circuit$1) chip semiconductor) near5 (organic carbon polymer) and @pd>20030715	USPAT; US-PGPUB	2003/07/27 18:11			0
BRS	L23	0	(flexible flexibility bend$4) near5 (ic (integrated adj circuit$1) chip semiconductor) near5 (organic carbon) near5 polymer$2 and @pd>20030715	USPAT; US-PGPUB	2003/07/27 18:12			0

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24	BRS L24	0	(flexible flexibility bend$4) near5 (ic (integrated adj circuit$1) chip semiconductor) near5 (organic carbon) near5 polymer$2 and @pd>20030715	EPO; JPO; DERWENT; IBM_TDB	2003/07/27 18:12			0
25	BRS L25	0	(flexible flexibility bend$4) near5 (ic (integrated adj circuit$1) chip semiconductor) near5 (organic carbon polymer) and @pd>20030715	EPO; JPO; DERWENT; IBM_TDB	2003/07/27 18:12			0
26	IS& R L31	1	("6547151").PN.	USPAT; US-PGPUB	2003/07/27 18:50			0
27	BRS L56	9	(flexible flexibility bend$4) near5 (ic (integrated adj circuit$1) semiconductor) near5 paper	USPAT; US-PGPUB	2003/07/27 19:29			0
28	BRS L57	53	(flexible flexibility bend$4) near5 (ic (integrated adj circuit$1) semiconductor) near5 organic semiconductive) near5 organic	USPAT; US-PGPUB	2003/07/27 19:20			0
29	BRS L58	33	(flexible flexibility bend$4) near5 (ic (integrated adj circuit$1) semiconductor semiconductive) near5 organic	EPO; JPO; DERWENT; IBM_TDB	2003/07/27 19:20			0
30	BRS L59	5	(flexible flexibility bend$4) near5 (ic (integrated adj circuit$1) semiconductor) near5 paper	EPO; JPO; DERWENT; IBM_TDB	2003/07/27 19:29			0

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BRS	L67	819	340/572.1.ccls. not (340/572.7.ccls. 283/70.ccls. 162/163.ccls. 283/86.ccls. 235/451.ccls. 235/441.ccls. 283/72.ccls. 283/98.ccls. 283/83.ccls. 235/487.ccls. 235/492.ccls. 902/1.ccls. 902/25.ccls. 902/26.ccls. 902/29.ccls.)	USPAT; US-PGPUB	2003/07/27 20:26			0
BRS	L68	522	361/728.ccls. not (340/572.1.ccls. 340/572.7.ccls. 283/70.ccls. 162/163.ccls. 283/86.ccls. 235/451.ccls. 235/441.ccls. 283/72.ccls. 283/98.ccls. 283/83.ccls. 235/487.ccls. 235/492.ccls. 902/1.ccls. 902/25.ccls. 902/26.ccls. 902/29.ccls.)	USPAT; US-PGPUB	2003/07/27 20:33			0
BRS	L69	623	257/40.ccls. not (361/728.ccls. 340/572.1.ccls. 340/572.7.ccls. 283/70.ccls. 162/163.ccls. 283/86.ccls. 235/451.ccls. 235/441.ccls. 283/72.ccls. 283/98.ccls. 283/83.ccls. 235/487.ccls. 235/492.ccls. 902/1.ccls. 902/25.ccls. 902/26.ccls. 902/29.ccls.)	USPAT; US-PGPUB	2003/07/27 20:53			0

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35	BRS L70	1403	257/774.ccls. not (257/40.ccls. 361/728.ccls. 340/572.1.ccls. 340/572.7.ccls. 283/70.ccls. 162/163.ccls. 283/86.ccls. 235/451.ccls. 235/441.ccls. 283/72.ccls. 283/98.ccls. 283/83.ccls. 235/487.ccls. 235/492.ccls. 902/1.ccls. 902/25.ccls. 902/26.ccls. 902/29.ccls.)	USPAT; US-PGPUB	2003/07/27 21:49			0
36	BRS L71	16	("4472627" "4609207" "4763927" "4783646" "5341428" "5537105" "5545885" "5566441" "5850524" "5880934" "5888624" "5917178" "5984190" "6050494" "6111506" "6209098").PN.	USPAT	2003/07/27 21:35			0
37	BRS L72	0	6547151.URPN.	USPAT	2003/07/27 21:38			0
38	BRS L73	1	tag near5 paper near5 (ic chip semiconductor) near5 (antenna coil)	USPAT; US-PGPUB	2003/07/27 21:40			0
39	BRS L74	10	paper near5 (ic chip semiconductor) near5 (antenna coil)	USPAT; US-PGPUB	2003/07/27 21:43			0
40	BRS L75	118	tag near5 (ic chip semiconductor) near5 (antenna coil)	USPAT; US-PGPUB	2003/07/27 21:43			0
41	BRS L76	8	tag near5 (ic chip semiconductor) near5 print$3	USPAT; US-PGPUB	2003/07/27 21:47			0

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42	IS&R	L77	1	("6215402").PN.	USPAT; US-PGPUB	2003/07/27 21:47			0
43	BRS	L78	160	340/572.8.ccls. not (257/774.ccls. 257/40.ccls. 361/728.ccls. 340/572.1.ccls. 340/572.7.ccls. 283/70.ccls. 162/163.ccls. 283/86.ccls. 235/451.ccls. 235/441.ccls. 283/72.ccls. 283/98.ccls. 283/83.ccls. 235/487.ccls. 235/492.ccls. 902/1.ccls. 902/25.ccls. 902/26.ccls. 902/29.ccls.)	USPAT; US-PGPUB	2003/07/27 21:50			0

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101 BRS	0	(Krul-Johannes.in. Hart-Cornelius-Maria.in. DeLeeuw-Dagobert-Michel.in. DeHesse-Wilhelm-Bernardus.in. Matters-Marco.in.) and @pd>20021031	USPAT; US-PGPUB; EPO; JPO	2003/07/15 08:03				0
102 BRS	5	(Krul-J.in. Hart-C.in. DeLeeuw-D.in. DeHesse-W.in. Matters-M.in.) and @pd>20021031	DERWENT	2003/07/15 08:05				0
103 BRS	8	((paper cardboard) near5 (IC chip)) same (thread strip security forgery authentic$3) and @pd>20021031	USPAT; US-PGPUB	2003/07/15 08:09				0
104 BRS	2	((paper cardboard) near5 (IC chip)) same (organic polymer) and @pd>20021031	USPAT; US-PGPUB	2003/07/15 08:19				0
105 BRS	0	((paper cardboard currency passport) near5 (ic chip semiconduct$3)) same (security near2 (strip thread)) and @pd>20021031	USPAT; US-PGPUB	2003/07/15 08:22				0

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107 BRS	0	((paper cardboard currency passport) near5 (ic chip semiconduct$3)) same (organic near2 polymer) and @pd>20021031	USPAT; US-PGPUB	2003/07/15 08:23			0
108 BRS	0	conduct$3 near5 (security near2 (strip thread)) and @pd>20021031	USPAT; US-PGPUB	2003/07/15 08:23			0
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111 BRS	8	(security near2 (strip thread)) same (hologram holographic) and @pd>20021031	USPAT; US-PGPUB	2003/07/15 08:25			0
112 BRS	2	((paper cardboard currency passport) near5 (ic chip semiconduct$3)) same (noncontact (non adj contact) contactlessly inductive capacitive) and @pd>20021031	USPAT; US-PGPUB	2003/07/15 08:54			0

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115 BRS	3	(ic circuit semiconductive semiconductor) same (polyimide adj10 polyaniline) and @pd>20021031	USPAT; US-PGPUB	2003/07/15 09:10			0
116 BRS	8	polyimide adj10 polyaniline and @pd>20021031	USPAT; US-PGPUB	2003/07/15 09:13			0
117 BRS	19	(security near2 (strip thread)) same (size thickness width thick) and @pd>20021031	USPAT; US-PGPUB	2003/07/15 09:17			0
118 BRS	60	(banknote$1 (bank adj note$1) passport (security adj1 document$1 paper$1)) same (IC chip circuit semiconductor semiconducting) and @pd>20021031	USPAT; US-PGPUB	2003/07/15 09:27			0

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120 BRS	32	(banknote$1 (bank adj note$1) passport (security adj1 (document$1 paper$1 thread$1 strip$1))) same (IC chip circuit semiconductor semiconducting) and @pd>20021031	EPO; JPO; DERWENT; IBM_TDB	2003/07/15 10:06			0
121 BRS	9506	(flexible flexibility bend$4) near5 (ic (integrated adj circuit$1) chip semiconductor)	USPAT; US-PGPUB	2003/07/15 10:09			0
122 BRS	134	(flexible flexibility bend$4) near5 (ic (integrated adj circuit$1) chip semiconductor) near5 (organic carbon polymer)	USPAT; US-PGPUB	2003/07/15 12:46			0
123 BRS	7	(flexible flexibility bend$4) near5 (ic (integrated adj circuit$1) chip semiconductor) near5 (organic carbon) near5 polymer$2	USPAT; US-PGPUB	2003/07/15 12:40			0

Type	Hits	Search Text	DBs	Time Stamp	Comments Error Definition	Errors
124 BRS	5	(flexible flexibility bend$4) near5 (ic (integrated adj circuit$1) chip semiconductor) near5 (organic carbon) near5 polymer$2	EPO; JPO; DERWENT; IBM_TDB	2003/07/15 12:40		0
125 BRS	71	(flexible flexibility bend$4) near5 (ic (integrated adj circuit$1) chip semiconductor) near5 (organic carbon polymer)	EPO; JPO; DERWENT; IBM_TDB	2003/07/15 12:47		0